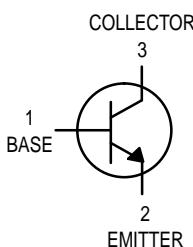


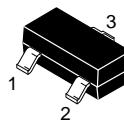
Low Noise Transistors

NPN Silicon



MMBT5088LT1 MMBT5089LT1*

*Motorola Preferred Device



CASE 318-08, STYLE 6
SOT-23 (TO-236AB)

MAXIMUM RATINGS

Rating	Symbol	5088LT1	5089LT1	Unit
Collector-Emitter Voltage	V_{CEO}	30	25	Vdc
Collector-Base Voltage	V_{CBO}	35	30	Vdc
Emitter-Base Voltage	V_{EBO}		4.5	Vdc
Collector Current — Continuous	I_C		50	mAdc

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Total Device Dissipation FR-5 Board ⁽¹⁾ $T_A = 25^\circ\text{C}$ Derate above 25°C	P_D	225 1.8	mW mW/ $^\circ\text{C}$
Thermal Resistance, Junction to Ambient	$R_{\theta JA}$	556	$^\circ\text{C}/\text{W}$
Total Device Dissipation Alumina Substrate, ⁽²⁾ $T_A = 25^\circ\text{C}$ Derate above 25°C	P_D	300 2.4	mW mW/ $^\circ\text{C}$
Thermal Resistance, Junction to Ambient	$R_{\theta JA}$	417	$^\circ\text{C}/\text{W}$
Junction and Storage Temperature	T_J, T_{stg}	-55 to +150	$^\circ\text{C}$

DEVICE MARKING

MMBT5088LT1 = 1Q; MMBT5089LT1 = 1R

ELECTRICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$ unless otherwise noted)

Characteristic	Symbol	Min	Max	Unit
OFF CHARACTERISTICS				
Collector-Emitter Breakdown Voltage ($I_C = 1.0 \text{ mA}, I_B = 0$)	$V_{(BR)CEO}$ MMBT5088 MMBT5089	30 25	— —	Vdc
Collector-Base Breakdown Voltage ($I_C = 100 \mu\text{A}, I_E = 0$)	$V_{(BR)CBO}$ MMBT5088 MMBT5089	35 30	— —	Vdc
Collector Cutoff Current ($V_{CB} = 20 \text{ Vdc}, I_E = 0$) ($V_{CB} = 15 \text{ Vdc}, I_E = 0$)	I_{CBO} MMBT5088 MMBT5089	— —	50 50	nAdc
Emitter Cutoff Current ($V_{EB(\text{off})} = 3.0 \text{ Vdc}, I_C = 0$) ($V_{EB(\text{off})} = 4.5 \text{ Vdc}, I_C = 0$)	I_{EBO} MMBT5088 MMBT5089	— —	50 100	nAdc

1. FR-5 = $1.0 \times 0.75 \times 0.062 \text{ in.}$

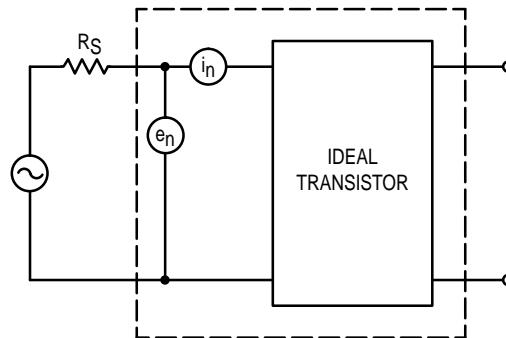
2. Alumina = $0.4 \times 0.3 \times 0.024 \text{ in. } 99.5\% \text{ alumina.}$

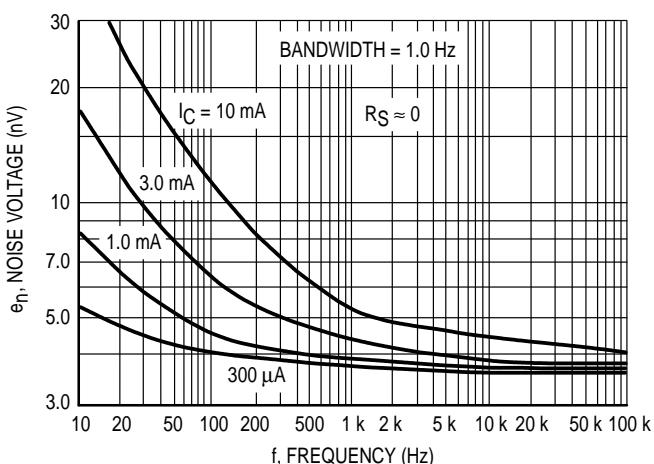
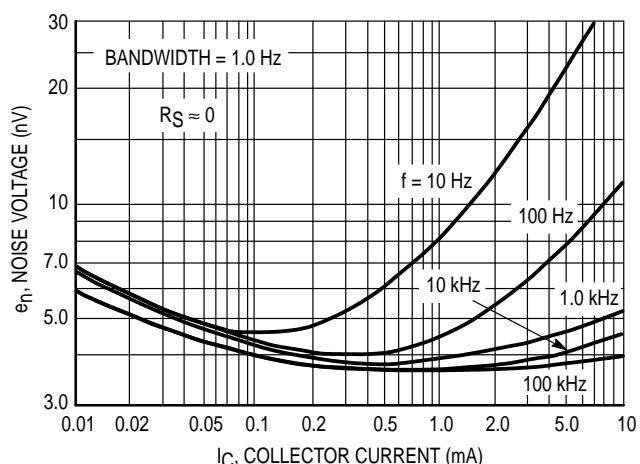
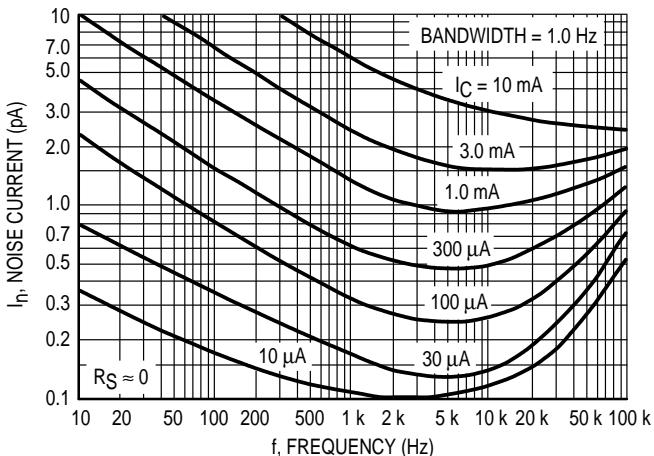
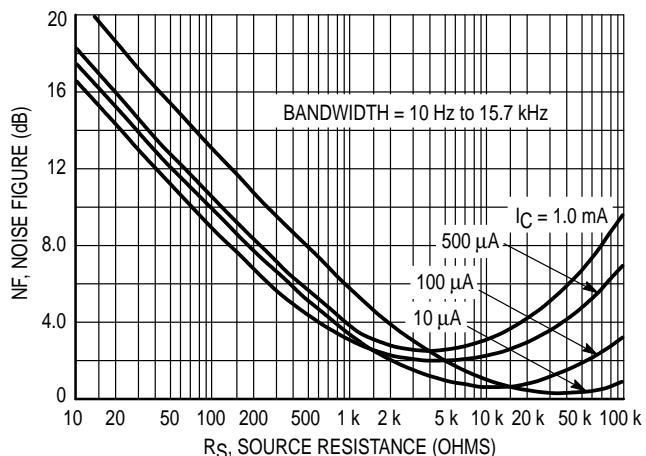
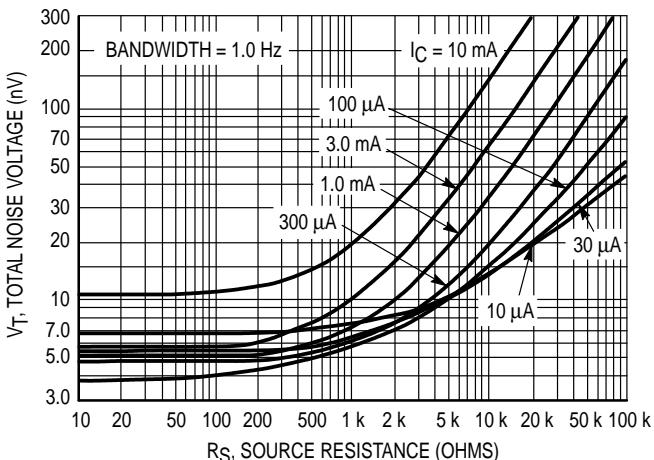
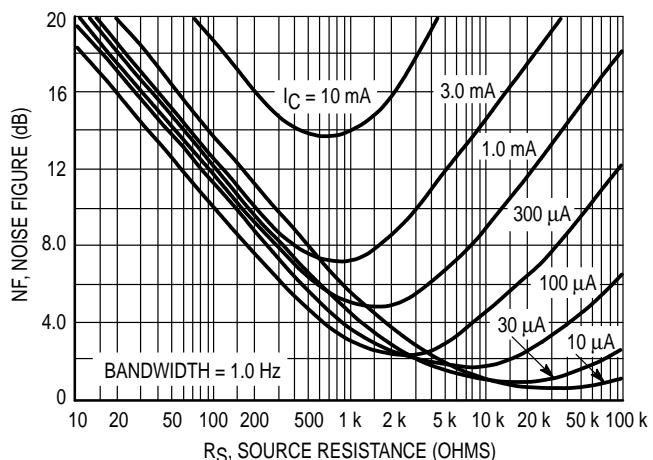
Thermal Clad is a trademark of the Bergquist Company.

Preferred devices are Motorola recommended choices for future use and best overall value.

MMBT5088LT1 MMBT5089LT1
ELECTRICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$ unless otherwise noted) (Continued)

Characteristic	Symbol	Min	Max	Unit
ON CHARACTERISTICS				
DC Current Gain ($I_C = 100 \mu\text{A}_{\text{dc}}$, $V_{CE} = 5.0 \text{ V}_{\text{dc}}$)	MMBT5088 MMBT5089	h_{FE}	300 400	900 1200
($I_C = 1.0 \text{ mA}_{\text{dc}}$, $V_{CE} = 5.0 \text{ V}_{\text{dc}}$)	MMBT5088 MMBT5089		350 450	— —
($I_C = 10 \text{ mA}_{\text{dc}}$, $V_{CE} = 5.0 \text{ V}_{\text{dc}}$)	MMBT5088 MMBT5089		300 400	— —
Collector-Emitter Saturation Voltage ($I_C = 10 \text{ mA}_{\text{dc}}$, $I_B = 1.0 \text{ mA}_{\text{dc}}$)	$V_{CE(\text{sat})}$	—	0.5	V_{dc}
Base-Emitter Saturation Voltage ($I_C = 10 \text{ mA}_{\text{dc}}$, $I_B = 1.0 \text{ mA}_{\text{dc}}$)	$V_{BE(\text{sat})}$	—	0.8	V_{dc}
SMALL-SIGNAL CHARACTERISTICS				
Current-Gain — Bandwidth Product ($I_C = 500 \mu\text{A}_{\text{dc}}$, $V_{CE} = 5.0 \text{ V}_{\text{dc}}$, $f = 20 \text{ MHz}$)		f_T	50	—
Collector-Base Capacitance ($V_{CB} = 5.0 \text{ V}_{\text{dc}}$, $I_E = 0$, $f = 1.0 \text{ MHz}$ emitter guarded)	C_{cb}	—	4.0	pF
Emitter-Base Capacitance ($V_{EB} = 0.5 \text{ V}_{\text{dc}}$, $I_C = 0$, $f = 1.0 \text{ MHz}$ collector guarded)	C_{eb}	—	10	pF
Small Signal Current Gain ($I_C = 1.0 \text{ mA}_{\text{dc}}$, $V_{CE} = 5.0 \text{ V}_{\text{dc}}$, $f = 1.0 \text{ kHz}$)	MMBT5088 MMBT5089	h_{fe}	350 450	1400 1800
Noise Figure ($I_C = 100 \mu\text{A}_{\text{dc}}$, $V_{CE} = 5.0 \text{ V}_{\text{dc}}$, $R_S = 10 \text{ k}\Omega$, $f = 1.0 \text{ kHz}$)	MMBT5088 MMBT5089	NF	— —	3.0 2.0
				dB


Figure 1. Transistor Noise Model

NOISE CHARACTERISTICS
 $(V_{CE} = 5.0 \text{ Vdc}, T_A = 25^\circ\text{C})$
NOISE VOLTAGE

Figure 2. Effects of Frequency

Figure 3. Effects of Collector Current

Figure 4. Noise Current

Figure 5. Wideband Noise Figure
100 Hz NOISE DATA

Figure 6. Total Noise Voltage

Figure 7. Noise Figure

MMBT5088LT1 MMBT5089LT1

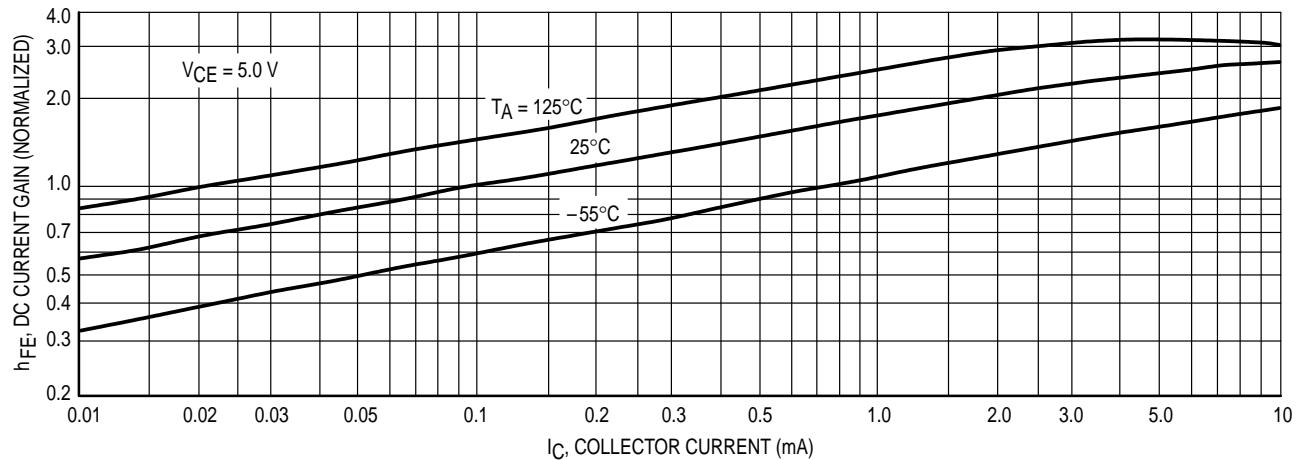


Figure 8. DC Current Gain

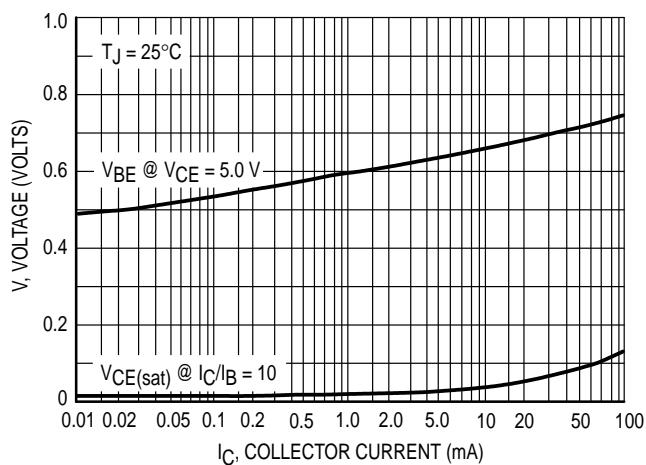


Figure 9. "On" Voltages

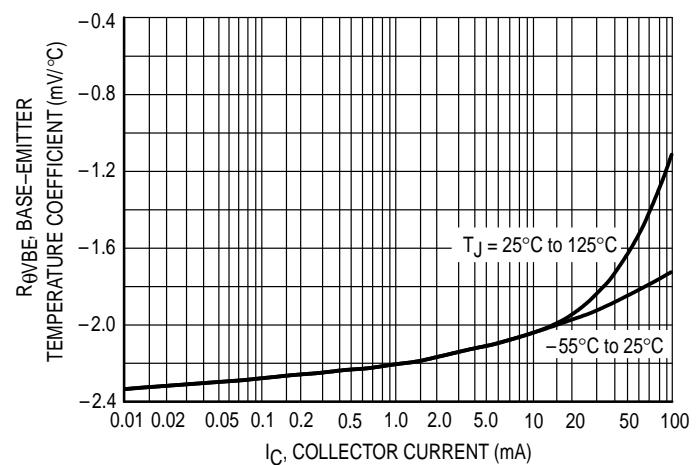


Figure 10. Temperature Coefficients

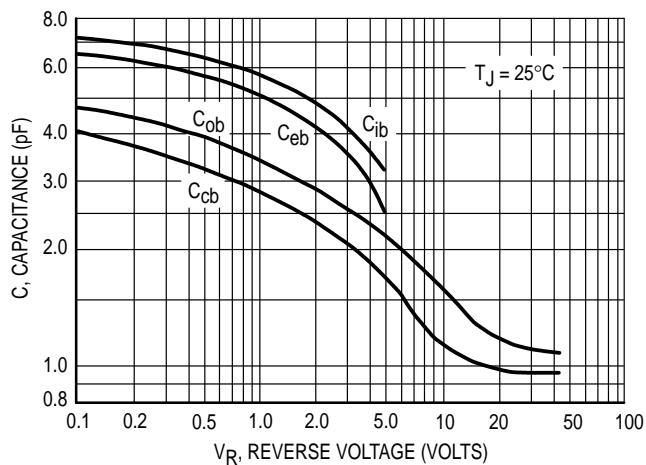


Figure 11. Capacitance

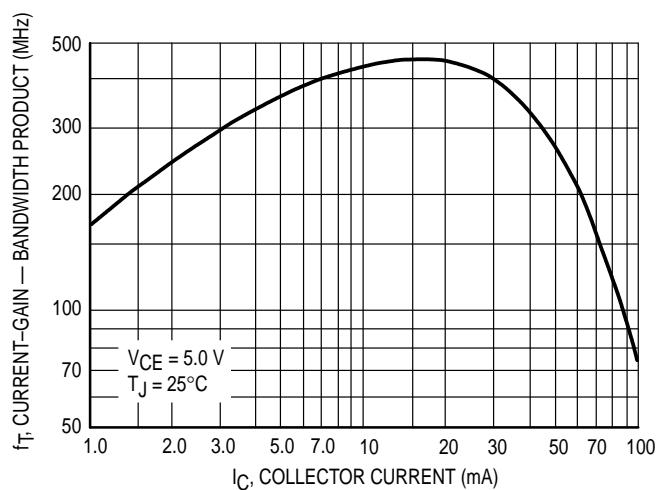


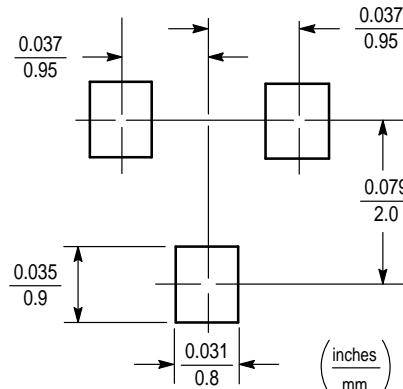
Figure 12. Current-Gain — Bandwidth Product

INFORMATION FOR USING THE SOT-23 SURFACE MOUNT PACKAGE

MINIMUM RECOMMENDED FOOTPRINT FOR SURFACE MOUNTED APPLICATIONS

Surface mount board layout is a critical portion of the total design. The footprint for the semiconductor packages must be the correct size to insure proper solder connection

interface between the board and the package. With the correct pad geometry, the packages will self align when subjected to a solder reflow process.



SOT-23

SOT-23 POWER DISSIPATION

The power dissipation of the SOT-23 is a function of the pad size. This can vary from the minimum pad size for soldering to a pad size given for maximum power dissipation. Power dissipation for a surface mount device is determined by $T_{J(max)}$, the maximum rated junction temperature of the die, $R_{\theta JA}$, the thermal resistance from the device junction to ambient, and the operating temperature, T_A . Using the values provided on the data sheet for the SOT-23 package, P_D can be calculated as follows:

$$P_D = \frac{T_{J(max)} - T_A}{R_{\theta JA}}$$

The values for the equation are found in the maximum ratings table on the data sheet. Substituting these values into the equation for an ambient temperature T_A of 25°C, one can calculate the power dissipation of the device which in this case is 225 milliwatts.

$$P_D = \frac{150^\circ\text{C} - 25^\circ\text{C}}{556^\circ\text{C/W}} = 225 \text{ milliwatts}$$

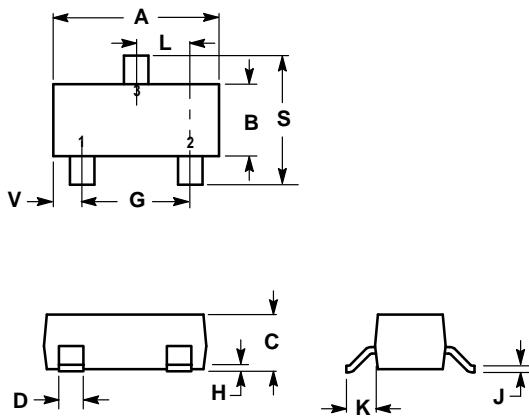
The 556°C/W for the SOT-23 package assumes the use of the recommended footprint on a glass epoxy printed circuit board to achieve a power dissipation of 225 milliwatts. There are other alternatives to achieving higher power dissipation from the SOT-23 package. Another alternative would be to use a ceramic substrate or an aluminum core board such as Thermal Clad™. Using a board material such as Thermal Clad, an aluminum core board, the power dissipation can be doubled using the same footprint.

SOLDERING PRECAUTIONS

The melting temperature of solder is higher than the rated temperature of the device. When the entire device is heated to a high temperature, failure to complete soldering within a short time could result in device failure. Therefore, the following items should always be observed in order to minimize the thermal stress to which the devices are subjected.

- Always preheat the device.
- The delta temperature between the preheat and soldering should be 100°C or less.*
- When preheating and soldering, the temperature of the leads and the case must not exceed the maximum temperature ratings as shown on the data sheet. When using infrared heating with the reflow soldering method, the difference shall be a maximum of 10°C.
- The soldering temperature and time shall not exceed 260°C for more than 10 seconds.
- When shifting from preheating to soldering, the maximum temperature gradient shall be 5°C or less.
- After soldering has been completed, the device should be allowed to cool naturally for at least three minutes. Gradual cooling should be used as the use of forced cooling will increase the temperature gradient and result in latent failure due to mechanical stress.
- Mechanical stress or shock should not be applied during cooling.

* Soldering a device without preheating can cause excessive thermal shock and stress which can result in damage to the device.

MMBT5088LT1 MMBT5089LT1**PACKAGE DIMENSIONS**

NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.1102	0.1197	2.80	3.04
B	0.0472	0.0551	1.20	1.40
C	0.0350	0.0440	0.89	1.11
D	0.0150	0.0200	0.37	0.50
G	0.0701	0.0807	1.78	2.04
H	0.0005	0.0046	0.013	0.100
J	0.0034	0.0070	0.085	0.177
K	0.0180	0.0236	0.45	0.60
L	0.0350	0.0401	0.89	1.02
S	0.0830	0.0984	2.10	2.50
V	0.0177	0.0236	0.45	0.60

STYLE 6:
 PIN 1. BASE
 2. Emitter
 3. Collector

**CASE 318-08
 SOT-23 (TO-236AB)
 ISSUE AE**

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